ABSTRACT

A first semiconductor chip (2) is bonded and secured to a second semiconductor chip (3) with a back surface of the first semiconductor chip (2) and a circuit forming surface (3X) of the second semiconductor chip (3) facing each other, and an inner portion of a support lead (6) is bonded and secured to the circuit forming surface (3X) of the second semiconductor chip (3). Such a configuration makes it possible to provide a semiconductor with a reduced thickness.